L	Hits	Search Text	DB	Time stamp
Number 29	383	batch same ("work piece" or wafer) same	USPAT;	2003/07/30
		vacuum	EPO; JPO;	15:11
			IBM TDB	
30	843	(batch or casette or boat) same ("work	USPĀT;	2003/07/30
		piece" or wafer) same vacuum	EPO; JPO;	15:15
	i -		IBM_TDB	
31	738			2003/07/30
		wafer) and vacuum		15:12
			IBM_TDB	i.
32	293	(proce or	USPAT;	2003/07/30
		wafer) and vacuum) and computer	EPO; JPO;	15:12
1			IBM_TLB	
33	48	(batch adj size) and ("work piece" or	USPAT;	2003/07/30
		wafer) and vacuum and (etch\$3 or	EPO; JPO;	15:14
	3,0000	deposit\$3 or clean\$3)	IBM_TDB	
34	19220	(batch or casette or boat) and ("work	USPAT;	2003/07/30
1		piece" or wafer or substrate) and (vacuum	EPO; JPO;	15:16
25	0000	or subatmospheric)	IBM_TDB	
35	2238	(batch or casette or boat) same ("work	USPAT;	2003/07/30
	1	piece" or wafer or substrate) same	EPO; JPO;	15:16
2.0	211	(vacuum or subatmospheric)	IBM_TDB	
36	311	((batch or casette or boat) same ("work	USPAT;	2003/07/30
		piece" or wafer or substrate) same	EPO; JPO;	15:17
		(vacuum or subatmospheric)) and	IBM_TDB	
		438/\$.ccls.	l	L.,,